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Authors: Minkyong Jung, Gibaek Lee, Jinsub Choi

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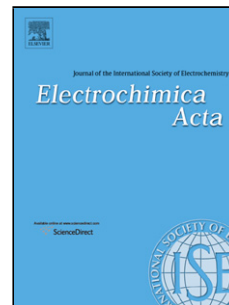
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**Electrochemical plating of Cu-Sn alloy in non-cyanide solution  
to substitute for Ni undercoating layer**

Minkyong Jung, Gibaek Lee<sup>\*</sup>, and Jinsub Choi<sup>\*</sup>

*Nano & Energy Material Lab., Department of Chemistry and Chemical Engineering,  
Inha University, Nam-gu, 22212, Incheon, South Korea*

<sup>\*</sup>Corresponding author.

E-mail: gibaek@inha.ac.kr (Gibaek Lee), jinsub@inha.ac.kr (Jinsub Choi);

Tel.: +82-32-860-7476, 82-32-860-7471

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